

Title (en)

METHOD OF AND WIRE BONDING APPARATUS FOR MANUFACTURING A TRANSDUCER

Title (de)

VERFAHREN UND DRAHTBOND-VORRICHTUNG ZUR HERSTELLUNG EINES WANDLERS

Title (fr)

PROCEDE ET DISPOSITIF DE CONNEXION DE FILS POUR LA FABRICATION D'UN TRANSDUCTEUR

Publication

**EP 0985132 A1 20000315 (EN)**

Application

**EP 98924461 A 19980528**

Priority

- GB 9801557 W 19980528
- GB 9710988 A 19970528
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Abstract (en)

[origin: WO9854545A2] A method of manufacturing a transducer for use in sensing or generating magnetic fields in a position detector is provided. The method uses wire bonding technology commonly used in the manufacture of integrated circuits. The method uses a wire laying device for controllably laying a wire in a desired pattern on to a substrate. The process of laying the wire on the wire includes the steps of sensing the current position of the wire laying device relative to the substrate, comparing the current position with an expected position derived from the desired pattern, controlling the relative movement between the wire laying device and the substrate in dependence upon the result of said comparison step and bonding the wire to the substrate to form the desired pattern.

IPC 1-7

**G01B 7/00**

IPC 8 full level

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CPC (source: EP US)

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